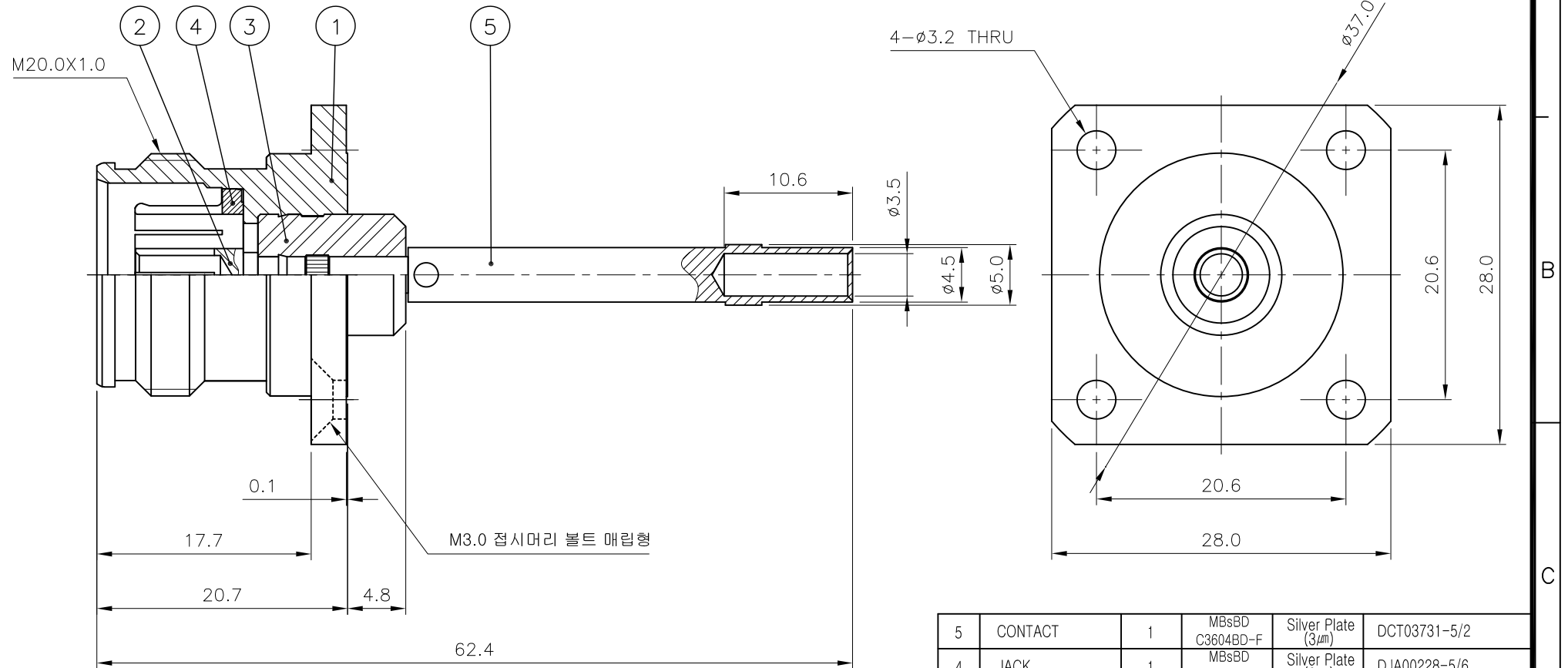


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
1	Initial Registration	T.J.KIM	J.H.YOUN	2016. 07. 19.
2	형상 및 길이 변경	S.L.SON	J.H.YOUN	2016. 11. 25.
3	PIN 형상 변경	S.L.SON	J.H.YOUN	2019. 08. 07.
4	조립공차 ±0.1 -> ±0.2 변경	S.Y.EUN	I.C.KIM	2020. 05. 12.



5	CONTACT	1	MBsBD C3604BD-F	Silver Plate (3 μ m)	DCT03731-5/2
4	JACK	1	MBsBD C3604BD-F	Silver Plate (3 μ m)	DJA00228-5/6
3	INSULATOR	1	TEFLON		DIN02919-N/1
2	CONTACT	1	BeCu C17300	Silver Plate (5 μ m)	DCT03729-5/2
1	BODY	1	MBsBD C3604BD-F	SUCO Plate (3 μ m)	DBD04187-5/2
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal ±0.2	DATE 2020. 05. 12.		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017	
	Angle ±1°	APPROVED BY I.C.KIM			
MATERIAL _____		CHECKED BY	TITLE 4.3-10 DC BLOCK JS-4H		
		DRAWN BY S.Y.EUN			
FINISH _____		SCALE 2/1	UNIT mm	A4	DWG NO. CN03635-7/4
					REVISION 4